

## **EPO-TEK® H20E-SLR-HVMX**

Technical Data Sheet For Reference Only Electrically Conductive Epoxy

Date: November 2019 Recommended Cure: 140°C / 10 Minutes

Rev: V
No. of Components: Two

Mix Ratio by Weight: 100 : 11

Specific Gravity: Part A: 2.61 Part B: 1.10

Pot Life: 19 Hours

**Shelf Life- Bulk:** One year at room temperature

May not achieve performance properties listed below

140°C / 35 Seconds 120°C / 15 Minutes 100°C / 2 Hours 80°C / 4 Hours

Minimum Alternative Cure(s):

## **NOTES:**

• Container(s) should be kept closed when not in use.

• Filled systems should be stirred thoroughly before mixing and prior to use.

• Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

<u>Product Description:</u> EPO-TEK® H20E-SLR-HVMX is a two-component, electrically conductive, epoxy for meter mix dispensing applications. It is designed for solar ribbon bonding of photovoltaic modules. It provides the electrical back-contact for ribbon stringing of solar cells into modules and panels. It is a higher viscosity version of EPO-TEK® H20E-SLR-MX.

<u>Typical Properties:</u> Cure condition: 140°C / 10 Minutes Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

PHYSICAL PROPERTIES:		
* Color (before cure):	Part A: Silver	Part B: Amber
* Consistency:	Smooth thixotropic paste	
* Viscosity (23°C) @ 50 rpm:	7,174	cPs
Thixotropic Index:	3.5	
* Glass Transition Temp:	≥ 88	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	51	x 10 <sup>-6</sup> in/in°C
Above Tg:	262	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	55	
Lap Shear @ 23°C:	1,844	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	400	°C
Weight Loss:		
@ 200°C:	0.36	%
@ 250°C:	1.27	%
@ 300°C:	2.40	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	886,816	psi
* Particle Size:	≤ 20	microns

ELECTRICAL AND THERMAL PROPERTIES:				
Thermal Conductivity:	1.5	W/mK		
* Volume Resistivity @ 23°C:	≤ 0.004	Ohm-cm		



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## **EPO-TEK® H20E-SLR-HVMX Advantages & Suggested Application Notes:**

- Meter mix format enables cost reduction by eliminating frozen shipments and freezer storage, maximizing pot life on the manufacturing floor, and reduction in precious metal waste.
- Strengths include dispensable rheology, fast cure, electrical contact resistance similar to solder and a long pot life.
- Enhanced green strength for holding ribbons in position prior to cure.
- Optimized viscosity for large needle dispensing.
- Photovoltaic Suggested Applications:
  - o Electrically conductive stringing of thin film, organic and crystalline Si solar cells.
  - Compatible with SnCu and AgCu metalized solar ribbons, and TCO substrates such as ITO, ZnO and SnO.
  - Versatility in ribbon bonding geometries, such as dotted or continuous line.
  - o In-line/in-situ curing processes in <1 minute at 140°C can be achieved.
  - Reliable green strength holds solar ribbons in position prior to cure.
  - Low temperature cure is well suited for CIGS and OPV/DSC solar cells requiring a low temperature process.
  - EVA film lamination post processing such as 150°C/15-30 minutes enhances performance properties.
  - o Suitable for use on IEC 61646, IEC 61730 and UL 1703 certified solar panels.